

10-11-01

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Docket No.: M-11928 US

October 9, 2001

Box Patent Application
Commissioner For Patents
Washington, D. C. 20231

Enclosed herewith for filing is a patent application, as follows:

Inventors: Jian Zhou and Hua Chu

Title: Method For Automatic De-Skewing Of Multiple Layer Wafer For Improved Pattern Recognition

- ☒ Return Receipt Postcard
- ☒ This Transmittal Letter (in duplicate)
- 12 pages Specification (not including claims)
- 4 pages Claims
- 1 page Abstract
- 6 Sheets of Drawings consisting of Figs. 1, 2, 3, 4, 5A, 5B, 6A, 6B, 6C, 6D, 6E and 6F
- ☒ Two identical compact discs in IBM-PC format and compatible with MS-Windows. A list attached as part of this transmittal letter includes the names, sizes, and creation dates of the files on the compact disks.
- 2 pages Declaration For Patent Application and Power of Attorney (UNSIGNED)
- 1 page NonPublication Request

☒ Applicants assert entitlement to small entity status for the attached patent application

CLAIMS AS FILED (fees computed under 37 CFR §1.9(f))

For	Number Filed		Number Extra		Rate		Basic Fee
Total Claims	24	-20 =	4	x	\$ 9.00	=	\$ 36.00
Independent Claims	7	-3 =	4	x	\$42.00	=	\$ 168.00
<input type="checkbox"/>	Fee of _____ for the first filing of one or more multiple dependent claims per application						\$
<input type="checkbox"/>	Fee for Request for Extension of Time						\$

Total fee for filing the patent application

\$ 574.00

EXPRESS MAIL LABEL NO:

EL 710 214 203 US

Respectfully submitted,



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MODIFIED PTO/SB/35 (11-00)

REQUEST AND CERTIFICATION UNDER 35 U.S.C. 122(b)(2)(B)(i)	Inventors	Jian Zhou and Hua Chu
	Title	Method For Automatic De-Skewing Of Multiple Layer Wafer For Improved Pattern Recognition
	Atty Docket Number	M-11928 US

I hereby certify that the invention disclosed in the attached application **has not and will not be** the subject of an application filed in another country, or under a multilateral agreement, that requires publication at eighteen months after filing. I hereby request that the attached application not be published under 35 U.S.C. 122(b).

October 9, 2001
Date


David C. Hsia
Attorney for Applicants
Reg. No.: 46,235

This request must be signed in compliance with 37 CFR 1.33(b) and submitted with the application **upon filing**.

Applicant may rescind this nonpublication request at any time. If applicant rescinds a request that an application not be published under 35 U.S.C. 122(b), the application will be scheduled for publication at eighteen months from the earliest claimed filing date for which a benefit is claimed.

If applicant subsequently files an application directed to the invention disclosed in the attached application in another country, or under a multilateral international agreement, that requires publication of applications eighteen months after filing, the applicant **must** notify the United States Patent and Trademark Office of such filing within forty-five (45) days after the date of the filing of such foreign or international application. **Failure to do so will result in abandonment of this application (35 U.S.C. 122(b)(2)(B)(iii)).**